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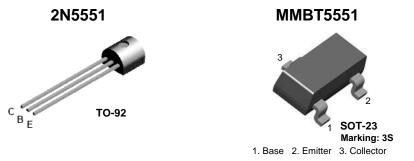


June 2009

# 2N5551 / MMBT5551 NPN General Purpose Amplifier

### **Features**

- This device is designed for general purpose high voltage amplifiers and gas discharge display drivers.
- Suffix "-C" means Center Collector in 2N5551 (1. Emitter 2. Collector 3. Base)
- Suffix "-Y" means  $h_{E}$  180~240 in 2N5551 (Test condition :  $I_C$  = 10mA,  $V_{CE}$  = 5.0V)



## **Absolute Maximum Ratings** \* $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Value	Units	
V <sub>CEO</sub>	Collector-Emitter Voltage	160	V	
V <sub>CBO</sub>	Collector-Base Voltage	180	V	
V <sub>EBO</sub>	Emitter-Base Voltage	6.0	V	
I <sub>C</sub>	Collector current - Continuous	600	mA	
T <sub>J</sub> , T <sub>stg</sub>	Junction and Storage Temperature	-55 to +150	°C	

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired. NOTES:

- 1. These ratings are based on a maximum junction temperature of 150 degrees C.
- 2. These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### Thermal Characteristics T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Max		Units	
		2N5551	*MMBT5551	Units	
P <sub>D</sub>	Total Device Dissipation Derate above 25°C	625 5.0	350 2.8	mW mW/°C	
$R_{ heta JC}$	Thermal Resistance, Junction to Case	83.3		°C/W	
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient	200	357	°C/W	

<sup>\*</sup> Device mounted on FR-4 PCB 1.6"  $\times$  1.6"  $\times$  0.06."

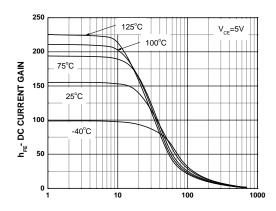
# **Electrical Characteristics** $T_A = 25\%$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units		
Off Charac	Off Characteristics						
V <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage *	$I_C = 1.0 \text{mA}, I_B = 0$	160		V		
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 100 \mu A, I_E = 0$	180		V		
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage I <sub>E</sub> = 10uA, I <sub>C</sub> = 0		6.0		V		
I <sub>CBO</sub>	Collector Cutoff Current	$V_{CB} = 120V, I_{E} = 0$ $V_{CB} = 120V, I_{E} = 0, T_{A} = 100^{\circ}C$		50 50	nA μA		
I <sub>EBO</sub>	Emitter Cutoff Current	$V_{EB} = 4.0V, I_{C} = 0$		50	nA		
On Charac	On Characteristics						
h <sub>FE</sub>	DC Current Gain	$I_C = 1.0$ mA, $V_{CE} = 5.0$ V $I_C = 10$ mA, $V_{CE} = 5.0$ V $I_C = 50$ mA, $V_{CE} = 5.0$ V	80 80 30	250			
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	$I_C = 10$ mA, $I_B = 1.0$ mA $I_C = 50$ mA, $I_B = 5.0$ mA		0.15 0.20	V V		
V <sub>BE(sat)</sub>	Base-Emitter On Voltage	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA I <sub>C</sub> = 50mA, I <sub>B</sub> = 5.0mA		1.0 1.0	V V		
Small Sign	Small Signal Characteristics						
f <sub>T</sub>	Current Gain Bandwidth Product	$I_C = 10$ mA, $V_{CE} = 10$ V, f = 100MHz	100		MHz		
C <sub>obo</sub>	Output Capacitance	V <sub>CB</sub> = 10V, I <sub>E</sub> = 0, f = 1.0MHz		6.0	pF		
C <sub>ibo</sub>	Input Capacitance	$V_{BE} = 0.5V, I_{C} = 0, f = 1.0MHz$		20	pF		
H <sub>fe</sub>	Small-Signal Current Gain	$I_C = 1.0 \text{ mA}, V_{CE} = 10 \text{ V}, f = 1.0 \text{kHz}$	50	250			
NF	Noise Figure	$I_C$ = 250 uA, $V_{CE}$ = 5.0 V, $R_S$ =1.0 kΩ, f=10 Hz to 15.7 kHz		8.0	dB		

### **Spice Model**

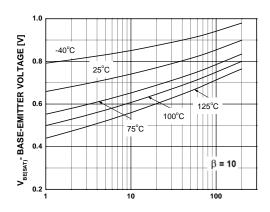
NPN (ls=2.511f Xti=3 Eg=1.11 Vaf=100 Bf=242.6 Ne=1.249 lse=2.511f lkf=.3458 Xtb=1.5 Br=3.197 Nc=2 lsc=0 lkr=0 Rc=1 Cjc=4.883p Mjc=.3047 Vjc=.75 Fc=.5 Cje=18.79p Mje=.3416 Vje=.75 Tr=1.202n Tf=560p ltf=50m Vtf=5 Xtf=8 Rb=10)

### **Typical Performance Characteristics**



I<sub>c</sub>- COLLECTOR CURRENT [mA]

Figure 1. Typical Pulsed Current Gain vs Collector Current



I - COLLECTOR CURRENT [mA]

Figure 3. Base-Emitter Saturation Voltage vs Collector Current

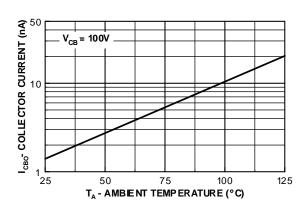
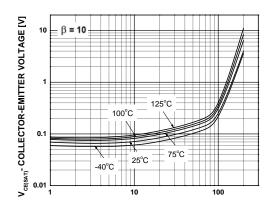
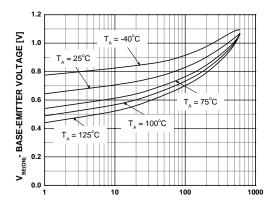


Figure 5. Collector Cutoff Current vs Ambient Temperature



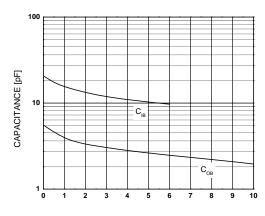
I<sub>c</sub>- COLLECTOR CURRENT [mA]

Figure 2. Collector-Emitter Saturation Voltage vs Collector Current



I\_- COLLECTOR CURRENT [mA]

Figure 4. Base-Emitter On Voltage vs Collector Current



REVERSE BIAS VOLTAGE [V]

Figure 6. Input and Output Capacitance vs Reverse Voltage

### **Typical Performance Characteristics** (Continued)

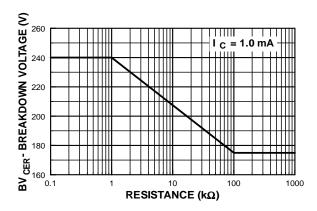


Figure 7. Collector- Emitter Breakdown Voltage with Resistance Between Emitter-Base

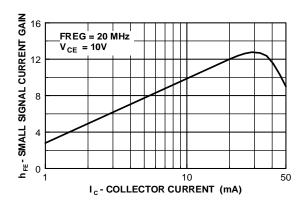


Figure 8. Small Signal Current Gain vs Collector Current

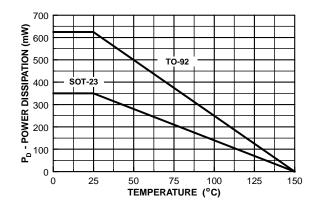


Figure 7. Power Dissipation vs Ambient Temperature





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